

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	713	250/370	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 08:21
L3	33	250/370 and solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 08:21
S46	165	(detect\$5 or sensor) and (solder with (protective or barrier)) and metallization	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/27 21:51
S47	267	(detect\$5 or sensor) and (UBM or (under adj bump adj metallization))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/23 19:11
S48	26	(detect\$5 or sensor) and (UBM or (under adj bump adj metallization)) and interposer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/27 18:48
S49	2	"5786597".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/27 18:12
S50	2	"5952646".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/27 18:12
S51	23	(detect\$5 or sensor) and (under adj bump adj metallization) and interposer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/27 18:48
S53	45	(encapsulant with solder) and interposer and (detect\$ or sensor) and pad	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/27 22:37